SPECIFICATION

COMMERCIALLY AVAILABLE

ITEM: WIDE BP SAW

PART NUMBER: SF0544020

RoHS

ISSUED / REVISION	ENGINEER APPROVED	DOCUMENT CHECKED	DRAFTSMAN
9/21/12 kn			
9/28/12 kn			
10/1/12 DS	03/01/2013 TFG	03/01/2013 TFG	03/01/2013 GL

***FILTRO**NETICS Inc*

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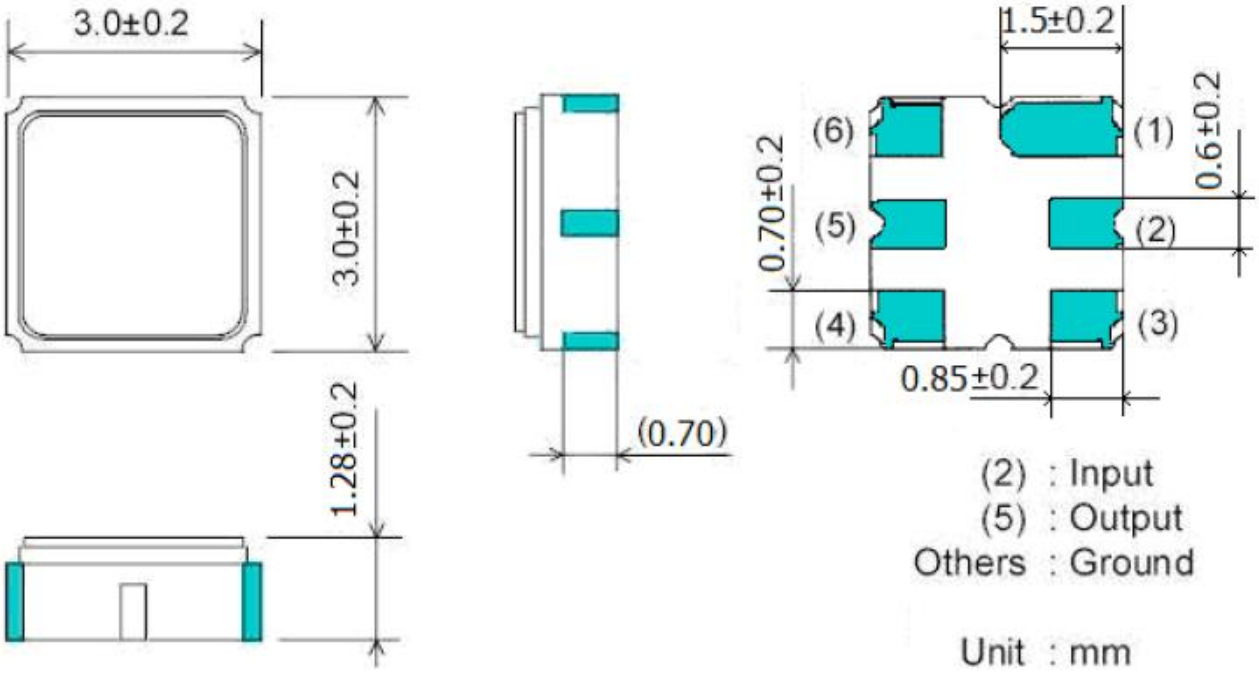
1. Electrical Specifications:

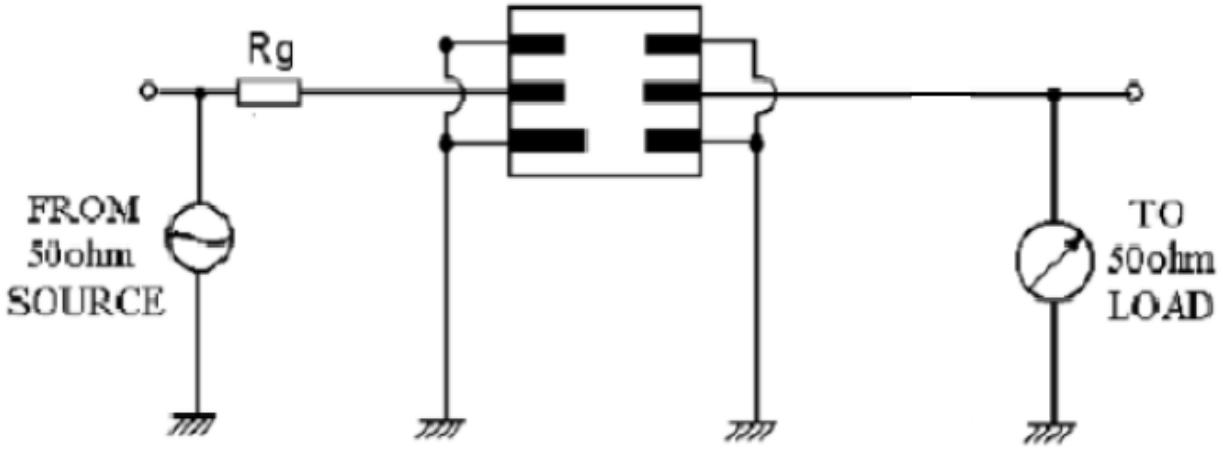
Parameter		Unit	Minimum	Typical	Maximum
Center Frequency		MHz	-	544	-
Insertion Loss (544 ±10MHz)		dB		2.2	3.5
Amplitude Ripple (544 ±10MHz)		MHz		0.5	1.5
Attenuation:	0.3MHz ~ Fo -50MHz	dB	40	58	-
	Fo -50MHz~Fo -30MHz		30	45	
	Fo +30MHz~Fo +50MHz		25	32	
	Fo +50MHz~1G		40	45	
	1G ~ 2.5G		20	45	
Input/Output Impedance		Ω	50		
Maximum Input Power		dBm	+15		
Operating Temperature		°C	-40 to +85		
Storage Temperature		°C	-40 to +85		

Marking:
544W

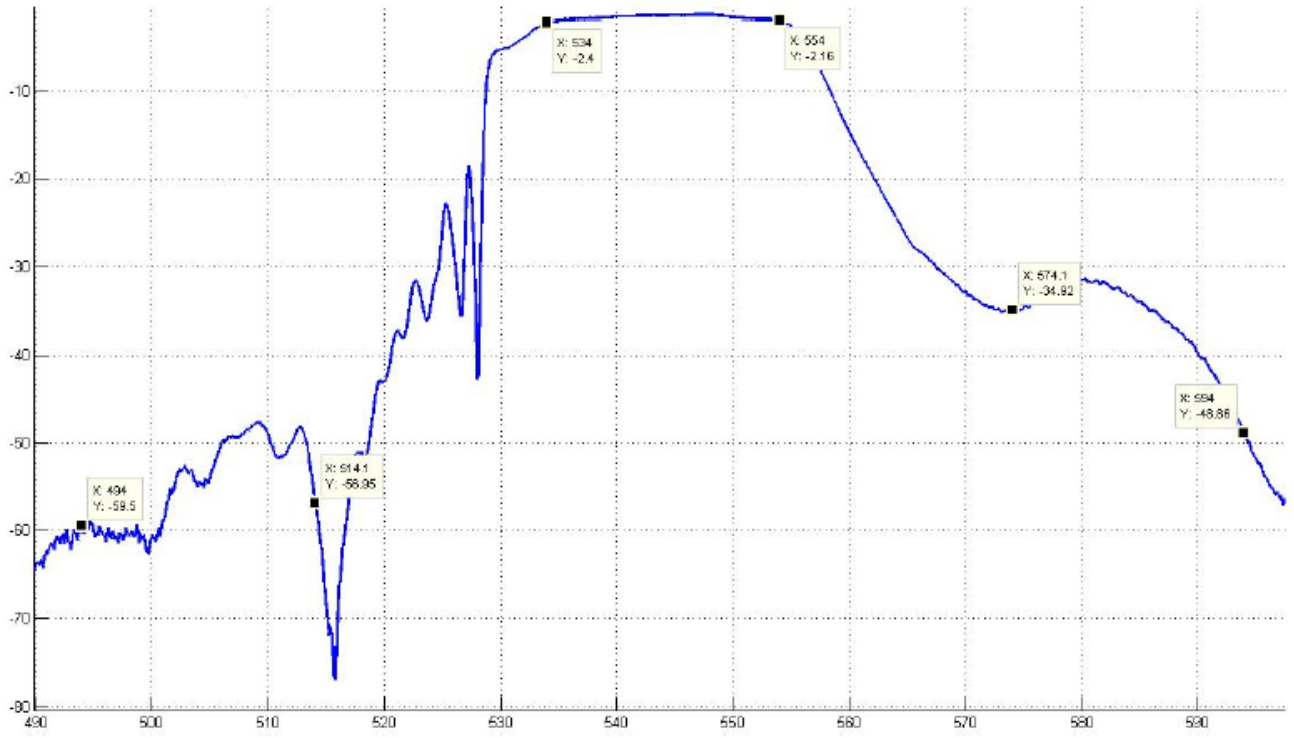
2. Dimension:



Test Circuit



3. Frequency Characteristics:



4. ENVIRONMENTAL CHARACTERISTICS

4-1 Temperature Cycling

Subject the device to a low temperature of -45°C for 30 minutes. Followed by a high temperature of +25°C for 5 minutes and a higher temperature of +85°C for 30 minutes. Then release the device into the room for 1 to 2 hours prior to the measurement. It shall meet the specifications in 3.3.

4-2 Resistance to Solder Heat

Submerge the device terminals into the solder bath at 260°C ±5°C for 10±1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 3.3.

4-3 Solderability

Submerge the device terminals into the solder bath at 248°C ±5°C for 5s. More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 3.3.

4-4 Mechanical Shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. The filter shall fulfill the specifications in 3.3.

4-5 Vibration

Subject the device to the vibration for 2 hours each in x, y and z axes with the amplitude of 1.5mm at 10 to 55hz. The filter shall fulfill the specifications in 3.3.

5. REMARKS

5.1 Static Voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic Cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

6. PACKAGING

6.1 Dimensions

(1) Carrier Tape: Figure 1
(2) Reel: Figure 2
(3) The product shall be packed properly noty to be damaged during transportation and storage.

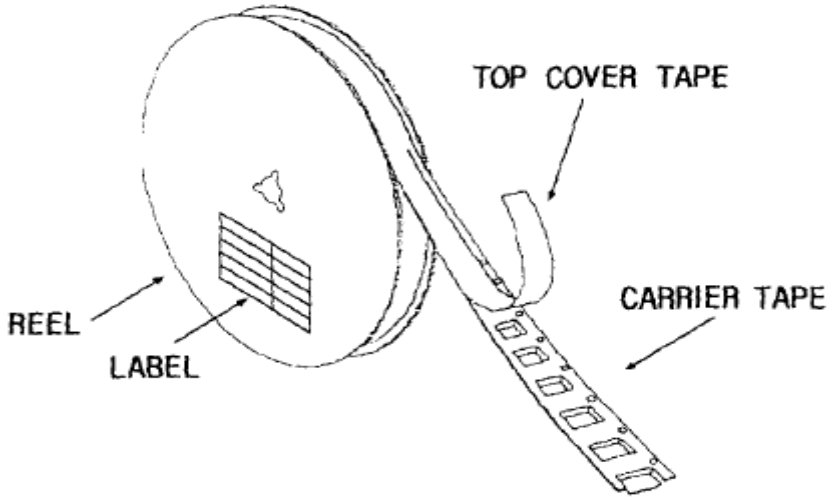
6.2 Reeling Quantity

1000 pcs/reel 7”

3000 pcs/reel 13”

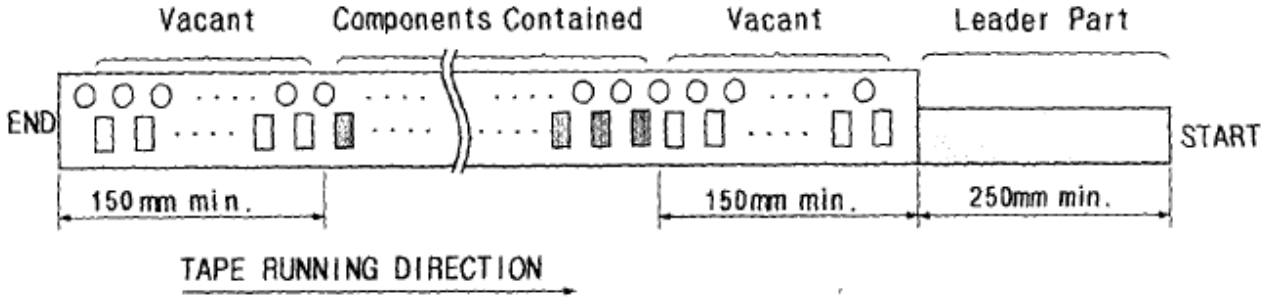
6.3 Taping Structure

(1) The tape shall be wound around the reel in the direction shown below.



(2) LABEL –Part too small for marking

(3) Leader part and vacant position specifications.



7. TAPE SPECIFICATIONS

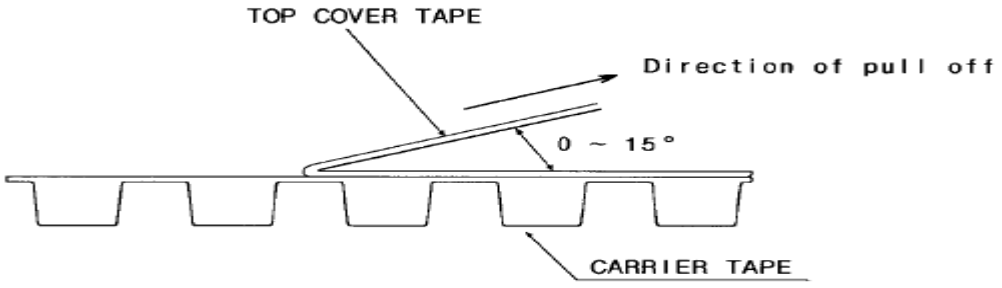
7.1 Tensile Strength of Carrier Tape: 4.4N/mm width

7.2 Top Cover Tape Adhesion (See the below figure)

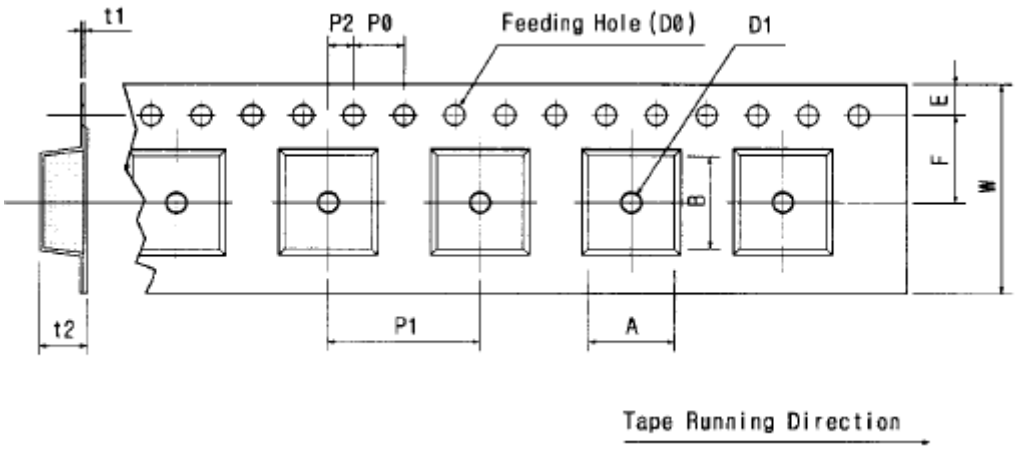
(1) pull off angle: 0~15°

(2) speed: 300mm/min.

(3) force: 20~70g



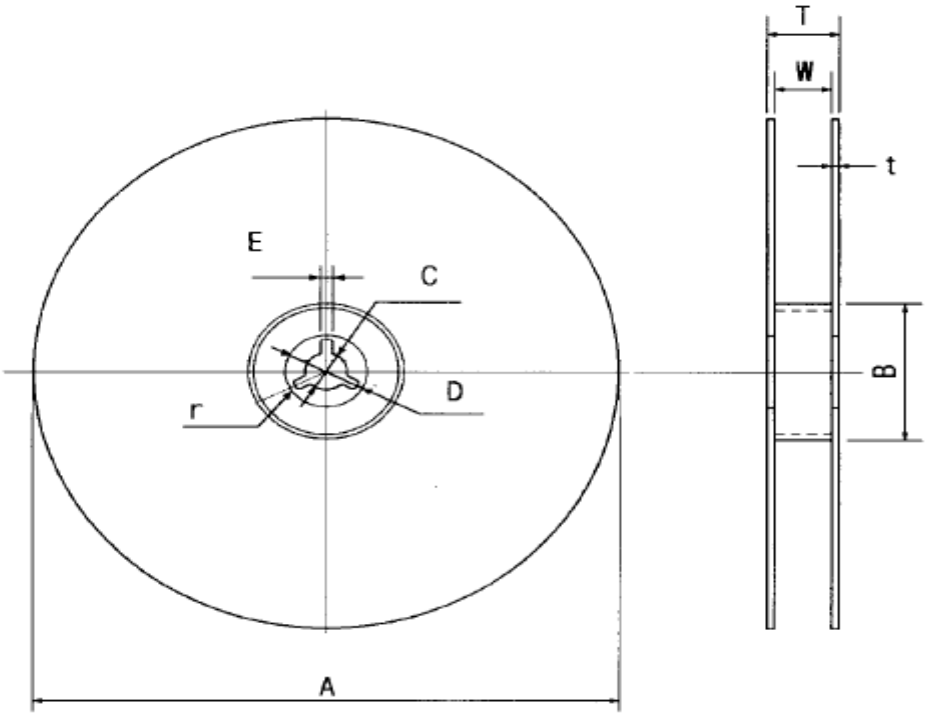
[Figure 1] Carrier Tape Dimension



[Unit:mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.00 ±0.30	5.50 ±0.10	1.75 ±0.10	4.00 ±0.10	8.00 ±0.10	2.00 ±0.10	Ø1.50	Ø1.0 ±0.25	0.25 ±0.05	1.65 ±0.10	4.04 ±0.10	4.10 ±0.10

[Figure 2]



[Unit:mm]

A	B	C	D	E	W	t	r
Ø330 ±1.0	Ø100 ±0.5	Ø13 ±0.5	Ø21 ±0.8	2 ±0.5	13 ±0.3	3 max.	1.0 max.